# **Refine Search**

### Search Results -

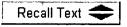
Terms	Documents
L1 and (cmp or polishing or planarizing or planarization or polish)	399

US Pre-Grant Publication Full-Text Database
US Patents Full-Text Database
US OCR Full-Text Database
EPO Abstracts Database
JPO Abstracts Database
Derwent World Patents Index
IBM Technical Disclosure Bulletins

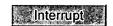
Search:

Database:

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## **Search History**

# DATE: Tuesday, February 07, 2006 Printable Copy Create Case

Set Name side by side	Query	Hit Count	Set Name result set
DB = 1	PGPB, $USPT$ , $USOC$ ; $PLUR = YES$ ; $OP = ADJ$		
<u>L5</u>	L1 and (cmp or polishing or planarizing or planarization or polish)	399	<u>L5</u>
<u>L4</u>	L2 and (cmp or polishing or planarizing or planarization or polish)	0	<u>L4</u>
DB = 1	EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ		
<u>L3</u>	L2 and (cmp or polishing or planarizing or planarization or polish)	4	<u>L3</u>
<u>L2</u>	L1	53	<u>L2</u>
DB = I	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD; PLUR=YES; OP=ADJ		
<u>L1</u>	(collection near3 particle or primary near2 (size or diameter) or crystallite near2 (size or diameter)) with (nm or nanometer) and size near3 distribution	2155	<u>L1</u>

### **END OF SEARCH HISTORY**